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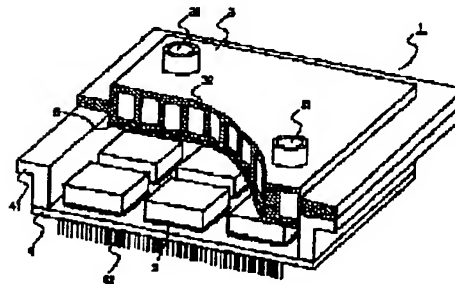
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(54) ELECTRONIC CIRCUIT DEVICE

(57) Abstract:

PROBLEM TO BE SOLVED: To realize an electronic circuit device which dissipates heat from a semiconductor element effectively and prevents hindrances due to thermal deformation.

SOLUTION: Resin 6 coated with grease or oil is arranged between a chip carrier 2 and thermal conductor 3. The chip carrier 2 is brought closely into contact with the thermal conductor 3 via the resin 6. Thereby the irregularities of height and inclination of the chip carrier 2 can be canceled by elasticity of the resin 6, and an superior state of close contact can be obtained. Contact thermal resistance due be significantly reduced by the satisfactory state of close contact and the application of grease or oil.



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